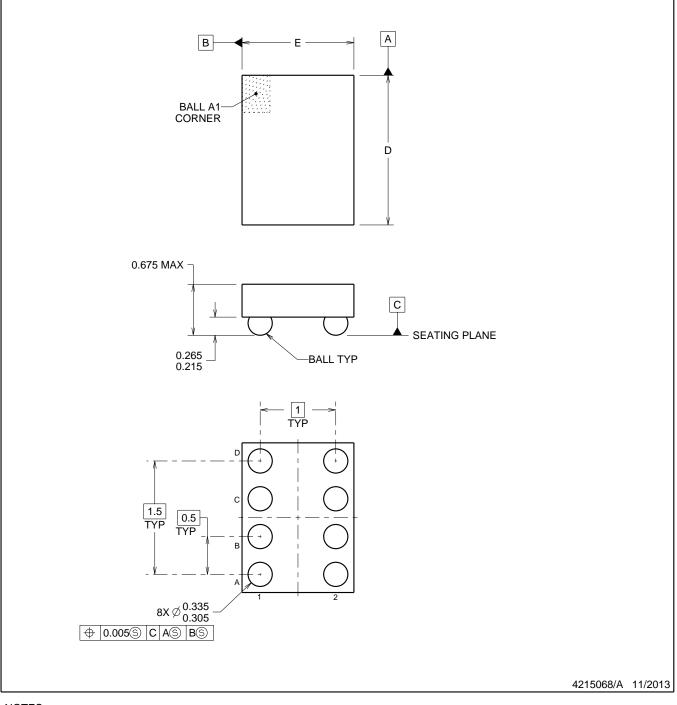
## PACKAGE OUTLINE



# DSBGA - 0.675 mm max height

DIE SIZE BALL GRID ARRAY



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.



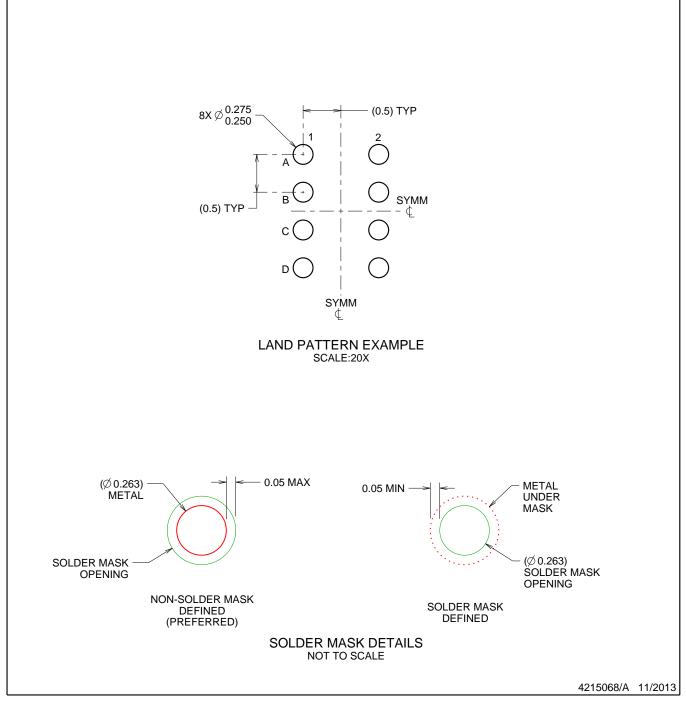
### YPA0008

### YPA0008

# EXAMPLE BOARD LAYOUT

### DSBGA - 0.675 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

3. Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. See Texas Instruments Literature No. SBVA017 (www.ti.com/lit/sbva017).

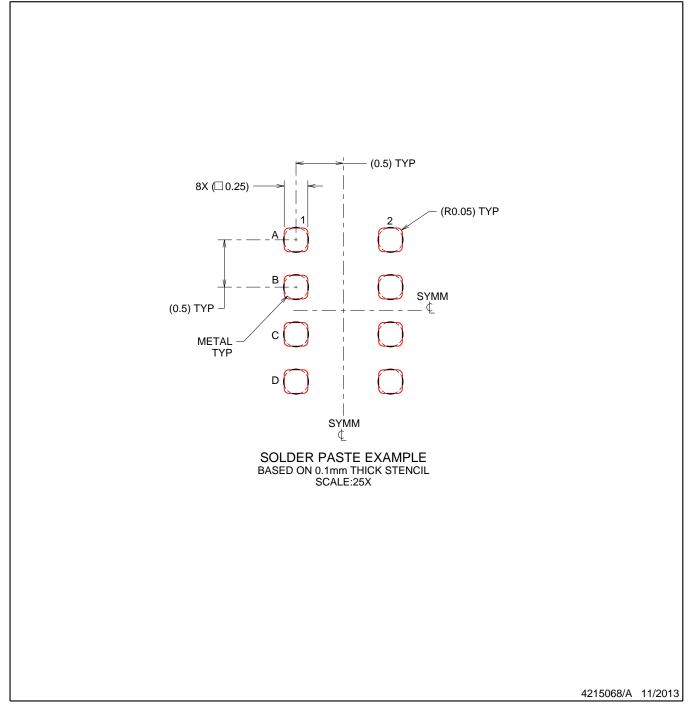


# EXAMPLE STENCIL DESIGN

### YPA0008

#### DSBGA - 0.675 mm max height

DIE SIZE BALL GRID ARRAY



NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.



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